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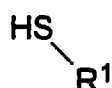
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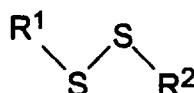
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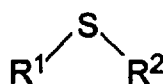
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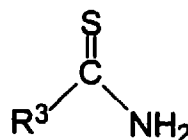
(A)



(B)



(C)



(D)

(57) Abstract: The present invention relates to a solution and to a method of treating copper surfaces, the copper surfaces being brought into contact with an acidic treatment liquid which contains hydrogen peroxide and at least one five-membered heterocyclic compound as well as additionally at least one microstructure modifying agent selected from the group comprising thioles A, disulfides B, sulfides, C and thioamides D having the respective general formulae wherein R¹ and R² = alkyl, alkenyl, aryl, aralkyl, especially benzyl, cycloalkyl and the derivatives thereof and R³ = R¹, R¹-O, R¹-S, amino or substituted amino, wherein R¹ and R² may especially be phenyl or substituted phenyl.

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